

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class* Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information								
Company Name *	Company Unique ID	Unique ID Authority	Response Date*					
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Aug 09, 2014 01:48 AM					
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David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com					

Requester Item Number	Mfr Ite	Mfr Item Number Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type
1N916	11	N916	DO-35 (Glass)				SUBCONTRACTOR		0.110000	g	Each
Manufacturing Process Information											
Terminal Finish	Base Alloy	J-STD-020 MSL Rating]	Peak Process Body Temperature		Max Time at Peak Temperature		No Reflow cycles		
Matte Tin (Sn)	Alloy 42	Not .	Not Applicable		С		seconds		Not A	Not Applicable	

^{*} Required Field

RoHS Material Composition Declaration

Declaration Type * Custom

RoHS Directive 2011/65/EU

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *

4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions | Supplier Acceptance * Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

7(c)-I-Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Declaration Signature

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

and Loneasto

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name DO-35 (Glass)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
CSS Wire	Other Ferrous alloys, non-stainless steels	75.025	Supplier		Carbon	0.375	7440-44-0	3409
			Supplier		Copper	26.300	7440-50-8	239091
			Supplier		Iron	48.200	7439-89-6	438182
			Supplier		Manganese	0.150	7439-96-5	1364
Chip	Other inorganic materials	0.021	Supplier		Silicon	0.021	7440-21-3	188
Dumet Wire	Other Ferrous alloys, non-stainless steels	8.491	Supplier		Carbon	0.013	7440-44-0	116
			Supplier		Cobalt	0.043	7440-48-4	386
			Supplier		Copper	1.910	7440-50-8	17364
			Supplier		Iron	3.730	7439-89-6	33909
			Supplier		Manganese	0.010	7439-96-5	93
			В	Nickel (external applications only)	Nickel	2.760	7440-02-0	25091
			Supplier		Silicon	0.026	7440-21-3	232
Encapsulation	Ceramics / Glass	23.468	В	Antimony/Antimony Compounds	Antimony Trioxide	0.012	1309-64-4	107
			Supplier		Diboron Trioxide *	0.705	1303-86-2	6409
			A	Lead/Lead Compounds	Lead (II,IV) oxide	14.300	1314-41-6	130000
			Supplier		Potassium Oxide	0.881	12136-45-7	8009
			Supplier		Silicon Dioxide, quartz	7.570	14808-60-7	68818
Ink	Marking Ink	0.021	Supplier		2,2,4-Trimethyl-1,3-pentanediol di is obutyrate	0.002	6846-50-0	16
			Supplier		Amino Resin	0.004	68002-20-0	36
			Supplier		C.I. pigment Violet	0.001	6358-30-1	6
			Supplier		C.I. pigment blue	0.001	147-14-8	5
			Supplier		Carbon Black	0.003	1333-86-4	25
			Supplier		Diethylene glycol 2-ethyhexyl-ether	0.004	1559-36-0	32
			Supplier		Phenolic resin	0.007	9003-35-4	61
			Supplier		Polyethylene	0.000	9002-88-4	3
			Supplier		Silica	0.001	112945-52-5	6
Plating	Other Nonferrous metals & alloys	2.630	Supplier		Tin	2.630	7440-31-5	23909